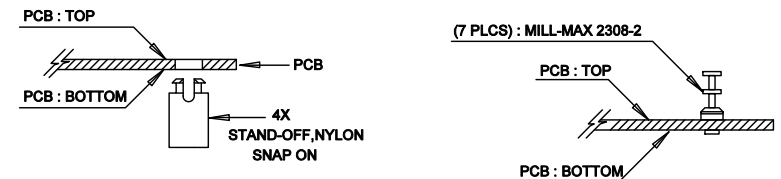


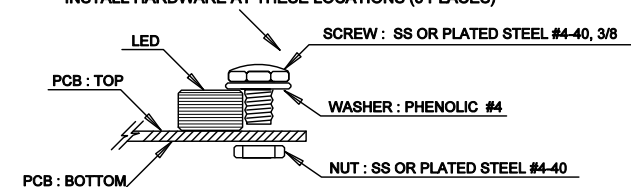
REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	1	PRODUCTION	MM	10-12-16

NOTES: UNLESS OTHERWISE SPECIFIED

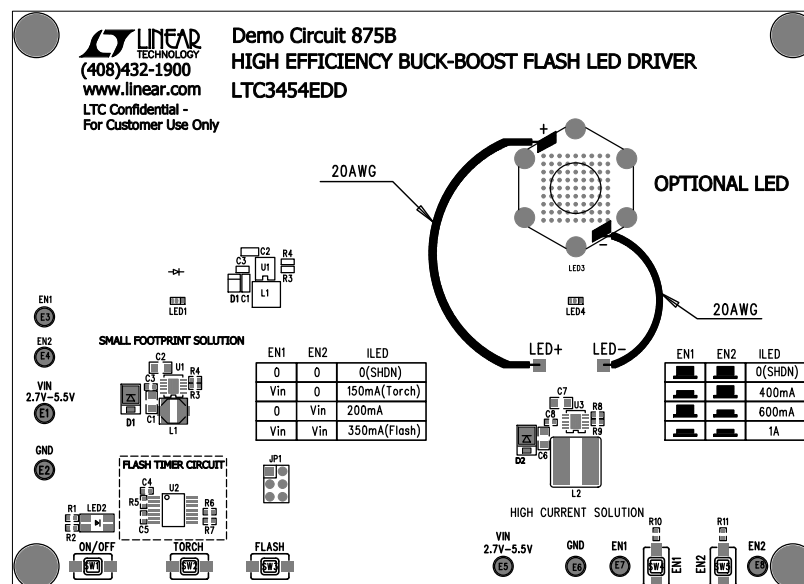
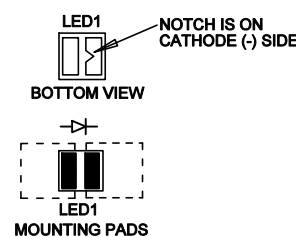
1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELCIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
6. INSTALL TURRETS AND 4 STAND-OFFS AT FOUR CORNERS AS SHOWN BELOW:



7. FOR OPTIONAL LED ASSEMBLY:
INSTALL HARDWARE AT THESE LOCATIONS (3 PLACES)



8. LED1 ASSEMBLY REQUIREMENTS:
HAND ASSEMBLY OF LED1 IS REQUIRED, SEE FIGURES BELOW.
MFG PART # Cree INC XQWDT-00-0000-00000LE51



APPROVALS		LINEAR TECHNOLOGY		
PCB DES.	RudyB	TITLE: TOP ASSEMBLY DRAWING: HIGH EFFICIENCY BUCK-BOOST FLASH LED DRIVER		
APP ENG.	BS			
		SIZE	IC NO.	LTC3454EDD
		N/A		DEMO CIRCUIT 875B
SCALE = NONE			REV.	1
		SHT 1 of 1		